

Atty. Dkt. No. 039153-0649 (H0982)

ABSTRACT

An integrated circuit includes multiple layers. A semiconductor-on-insulator (SOI) wafer can be used to house transistors. Two substrates or wafers can be bonded to form the multiple layers. A strained semiconductor layer can be between a silicon germanium layer and a buried oxide layer. A hydrogen implant can provide a breaking interface to remove a silicon substrate from the silicon germanium layer.

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